

FEATURES

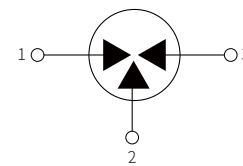
- | Size Design $\Phi 8.0 \times 10.0 \text{mm}$
- | High Current Handling Capability 10,000A @ 8/20 μs
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1



$\Phi 8.0 \times 10.0 \text{mm}$



APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.



Schematic Symbol

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Symbol	Rating	Unit
DC Blocking Voltage 1)	100V/s	120-180	V
Impulse Spark-over Voltage	At 1kV/ μ s	for 99 % of measured values \leq 650	V
	At 1kV/ μ s	Typical values of distribution \leq 600	V
Impulse Discharge Current 2)	8/20 μ s	10	KA
Insulation Resistance	DC=50V	\geq 1	G Ω
Capacitance at 1MHz	V _{DC} =0.5V	\leq 2	pF
Operating and Storage Temperature		-40~125	$^{\circ}$ C

1) In ionized mode

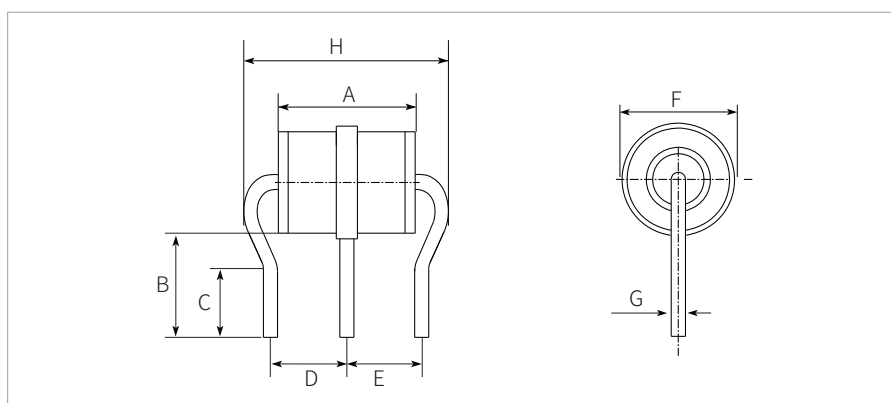
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IIEC 61643-311

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 $^{\circ}$ C; Time of dip soldering:10s,1time

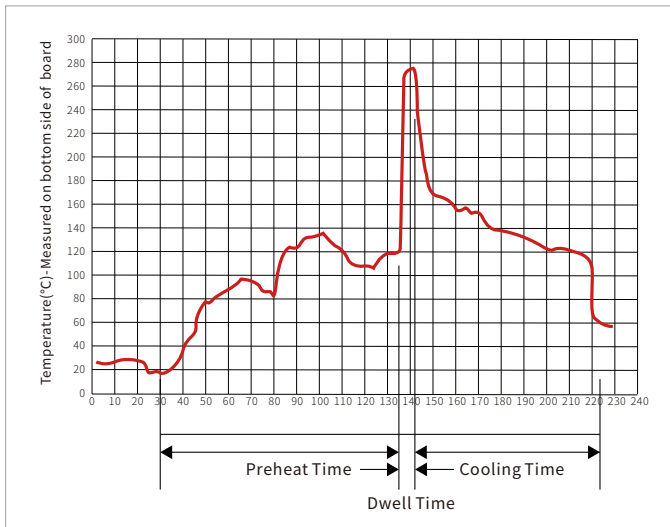
NOTE:Up-screen program can be specified by customer' s request via contacting Semiware service

PRODUCT DIMENSIONS




Ref.	Outline Dimensions
	Millimeters
A	10 \pm 0.3
B	7.0 \pm 0.5
C	4.0 \pm 0.5
D	4.4 \pm 0.3
E	4.4 \pm 0.3
F	Φ 8.0 \pm 0.2
G	Φ 1.0
H	13 \pm 1

WAVE SOLDERING



Wave Parameter		Lead-free assembly
Pre Heat	Temperature Min	100°C
	Temperature Max	150°C
	Time(min to max)	60 – 180 secs
Solder pot Temperature		280°C Max
Solder Dwell Time		2-5 seconds

ORDERING INFORMATION

Part Number	Size	Marking	Qty/pcs		
			Tray	Inner Box	Carton
SG3R08B150	Φ8.0*10.0mm	 SG150 08	100	500	6000

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By QR Code

Website



Wechat

To find your local partner within Semiware' s global website: www.semiware.com

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